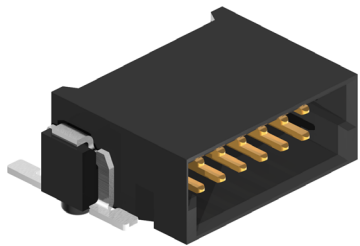
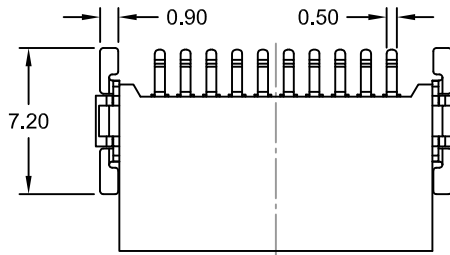


REV.	DESCRIPTION	DATE	DRAWN
A	New	05.12.2013	Ronny
D	add 100 pin: general update	29.05.2017	Ronny
E	update No. of Pin	10.09.2018	RH
F	general update	21.01.2019	Ronny
G	Remove Plating Options 95 and 9L5	21.01.2020	Cheng

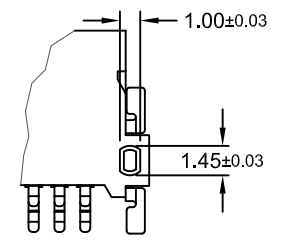
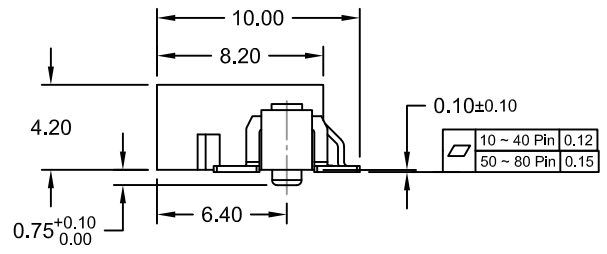
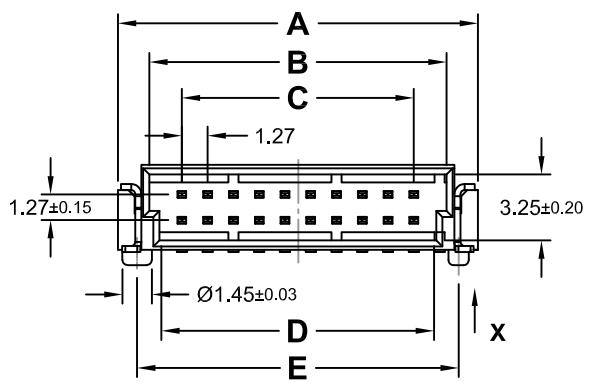


**Order Code**  
**MBC-xxx-BMH42-xx/11G**

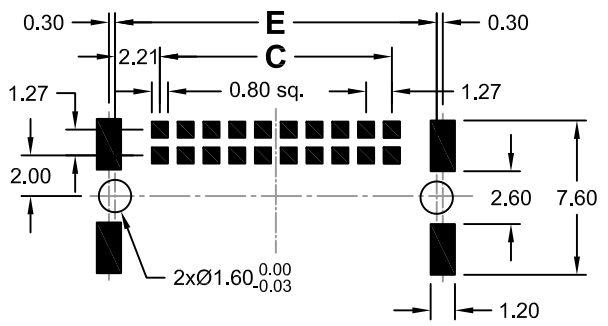
**Plating**

- 96 = Tin/10µ" Gold
- 97 = Tin/15µ" Gold
- 98 = Tin/30µ" Gold

No. of Pins	Dimension mm				
	A	B	C	D	E
010	11.43	8.30	5.08	7.30	9.50
012	12.70	9.57	6.35	8.57	10.77
016	15.24	12.11	8.89	11.11	13.31
020	17.78	14.65	11.43	13.65	15.85
026	21.59	18.46	15.24	17.46	19.66
030	24.13	21.00	17.78	20.00	22.20
032	25.40	22.27	19.05	21.27	23.47
040	30.48	27.35	24.13	26.35	28.55
050	36.83	33.70	30.48	32.70	34.90
068	48.26	45.13	41.91	44.13	46.33
080	55.88	52.75	49.53	51.75	53.95



View X



Recommended PCB Layout Top View  
(Tolerance: ±0.05)

**Specifications**

**Electrical**  
Current rating: 0.5 ~ 1.0A  
Insulation resistance: 10000MΩ min.  
Contact resistance: 25mΩ max.  
Withstanding voltage: 500V



**Material**

Contact: Copper Alloy  
Plating: Tin on solder, Gold on contact area  
Insulator: High Temperature Thermoplastic (black)  
UL 94V-0

Operating temperature: -55°C to +125°C  
Processing temperature: +260°C +0/-5°C  
for 5 seconds

**Packing: Reel**

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UNIT	mm	GENERAL TOLERANCE		DRAWN	Ronny	DATE	05.12.2013	DWG. NO.	MBC-BMH42/11G	SHEET 1/1
SCALE	Free	X.° ±	X. ±	CHECK	Cheng	DATE	21.01.2020	SERIES NO.	MBC-xxx-BMH42-xx/11G	REV. G
		.XX° ±	.XX ± 0.25	APPROVE	Fagi	DATE	21.01.2020			
		.XXX° ±	.XXX ±							

**Multi BUS/Backplane Connector**  
**B-Type Male SMT horizontal**  
1.27mm Pitch - Height 4.20mm  
*Compatible to ERNI INTERact® Series SMC Type*